

# Dual sourcing, single advantage: Building resilient eID solutions with Eviden and AdvanIDe

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# AGENDA

1. Advantages and Reasons for Dual Sourcing
2. EVIDEN Contribution Today and Tomorrow
3. Resilient eID Solutions – Technology Comparison
4. icoLAM<sup>®</sup> - inductive coupling LAMinate



# Advantages and Reasons for Dual Sourcing

- Performance Flexibility



- Cost Optimization



- Risk Mitigation



- Locked or pre-defined Solutions



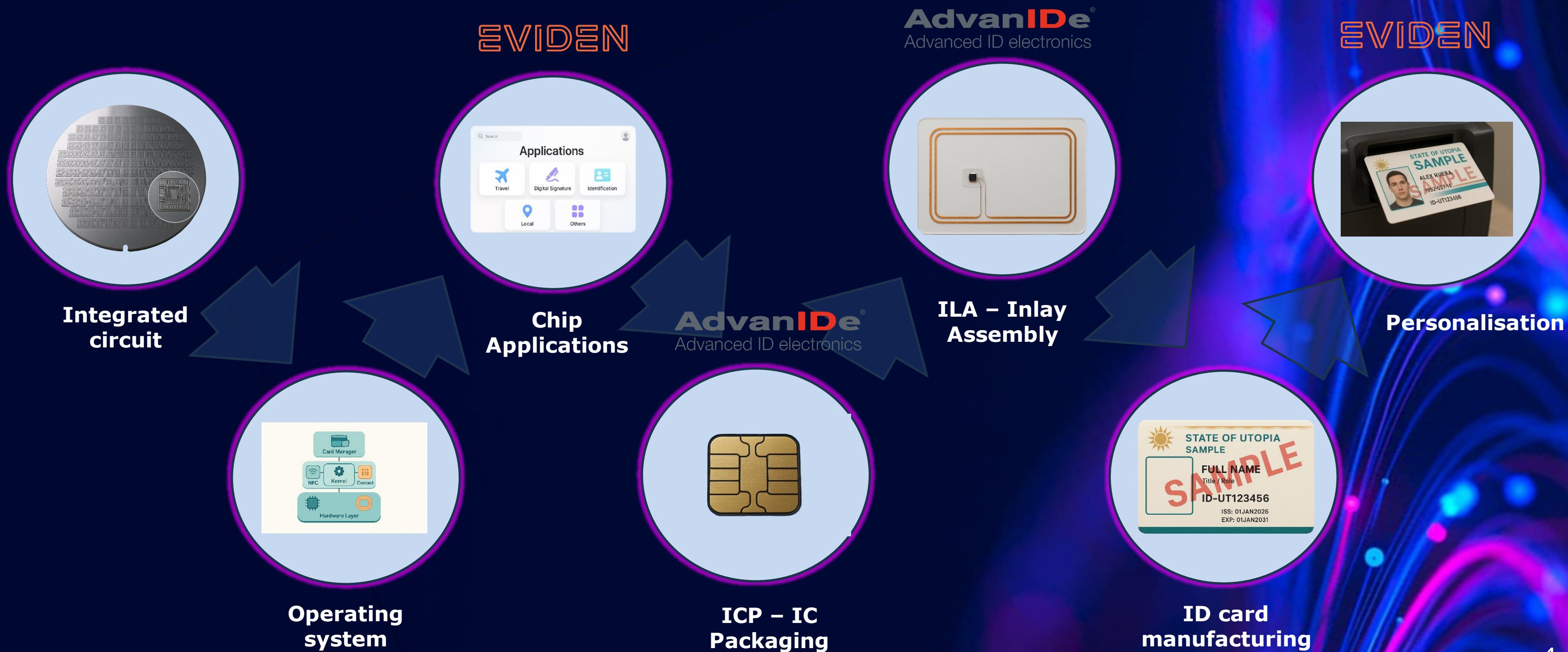
Customer-Centric Approach



- Supply Shortage



# eID Document Value Chain





# ePasslet Suite

## National sovereignty

Governments want control over solution, no single vendor black box

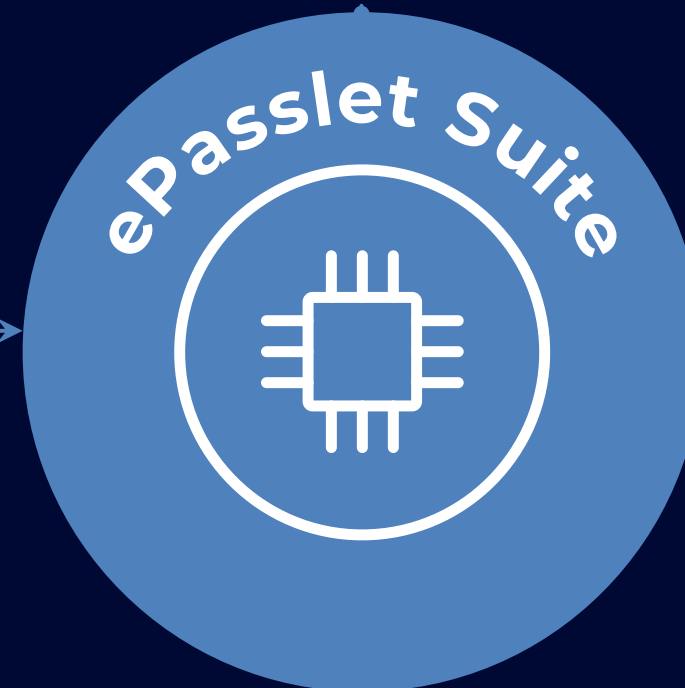
## Multi-application readiness

Operators want to add applications after issuance

## Less expense for card projects

More national involvement results in lower maintenance cost

## No vendor lock



30+ eID references across the globe

All major platforms supported  
Multiple applications on one chip

Simple integration with standard-compliant components  
Stock of CC-certified chips can be used for different eID use cases  
Wide spectrum of applications and use cases

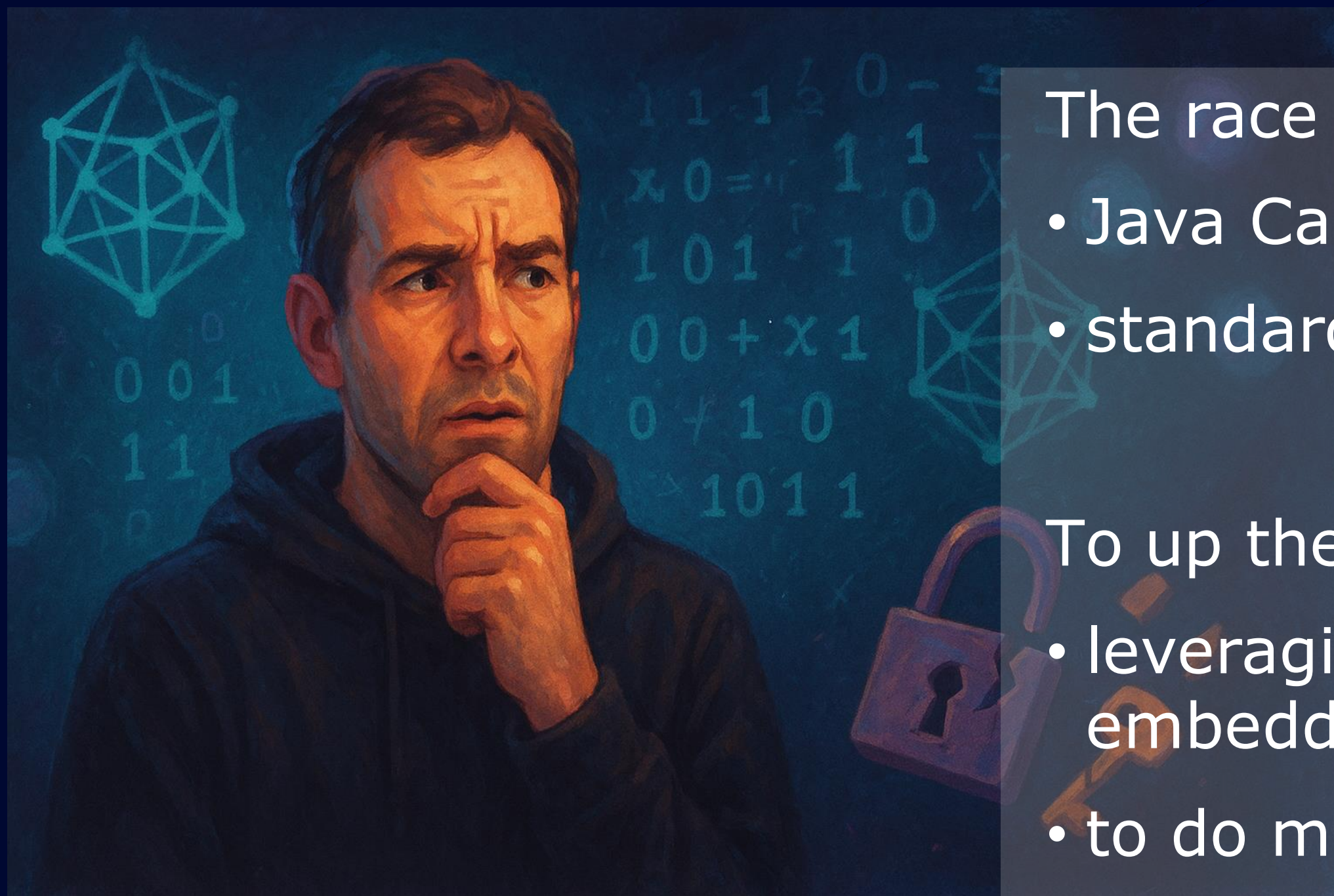
Enables creation of any eID document from one solution

# Challenges today

- Defining tomorrow's product roadmap
- Maintaining certifications
- Fulfilling a high variety of customer requirements
- Smooth plugging into mobile eID ecosystem



# Becoming ,PQC-ready`...



The race has begun but...

- Java Card platforms are not yet here
- standardization is not fast

To up the tempo, we are

- leveraging our developments in embedded security, PKI, infrastructure
- to do most of the work in advance



# Challenges tomorrow

- Seamless move to PQC-capable products
- Stability of upcoming specifications
- Certification (EUCC, CC 2022, new PPs)
- Real-life implementation of update in the field
- Finding a perfect fit into the future heterogeneous ecosystem
- Withstanding AI-driven security threats?



# Resilient eID Solutions – Technology Comparison

## Inductive Coupling DIF Technology

- No physical connection between module and antenna (RF transformer coupling)

## Galvanic Connection DIF Technology

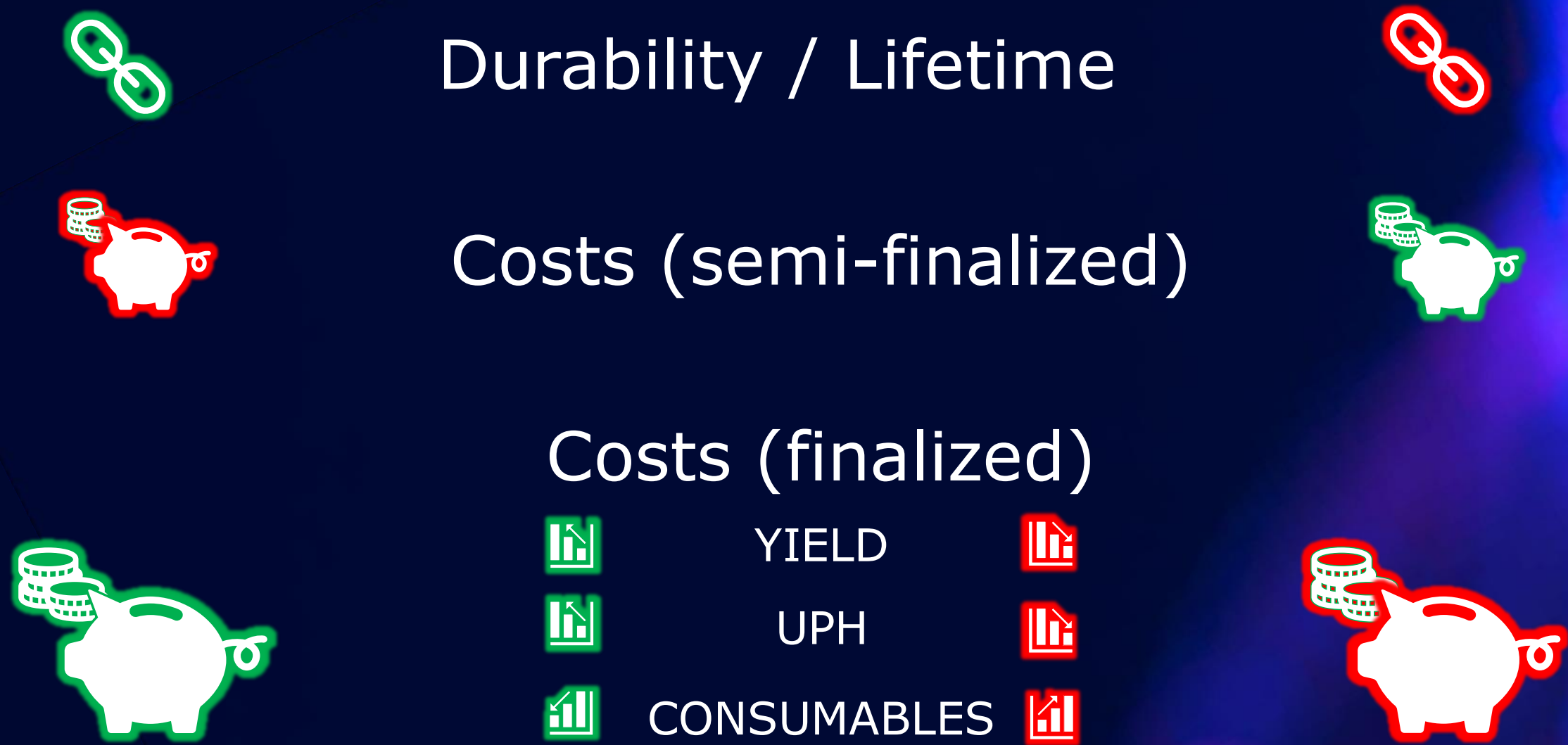
- Direct physical connection between chip module and antenna

Durability / Lifetime

Costs (semi-finalized)

Costs (finalized)

|                                                                                       |             |                                                                                       |
|---------------------------------------------------------------------------------------|-------------|---------------------------------------------------------------------------------------|
|  | YIELD       |  |
|  | UPH         |  |
|  | CONSUMABLES |  |
|  | CAPEX       |  |





# icoLAM<sup>®</sup> - inductive coupling LAMinate

## Hardware Independent

- Available on multiple Silicon Platforms
- One antenna design suitable for all these Platforms

## Solution & Substrate Independent

- icoLAM<sup>®</sup> ID
- icoLAM<sup>®</sup> PAY
- icoLAM<sup>®</sup> XS
- PC, PVC, PET-G & any eco-friendly recycled variant (e.g. rPVC) in mono- or multi-core variants

## Module Design & Customization

- 6-PIN or 8-PIN Gold, Silver/Palladium
- LoM<sup>®</sup> - Logo on Module





## Questions?

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